

SNH-377286

POSITIONING FLOWABLE SOLDER FOR
BONDING INTEGRATED CIRCUIT ELEMENTS

Abstract of the Disclosure

A solder mask defined bond pad or a non-solder mask defined bond pad may be configured to center the solder over the bond pad using either surface attractive forces or capillary action. In some embodiments, a stub trace may be provided, for example, in opposition to the real trace to provide a capillary counter-attractive force on the solder. In other embodiments, the surface attractive action of the edge of the solder mask may be utilized to center the solder. In still other embodiments, the natural attractive force of a trace on solder may be utilized to appropriately position solder where desired, for example, to line up with other solder deposits.

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